

A

B

C

D

E

F

A

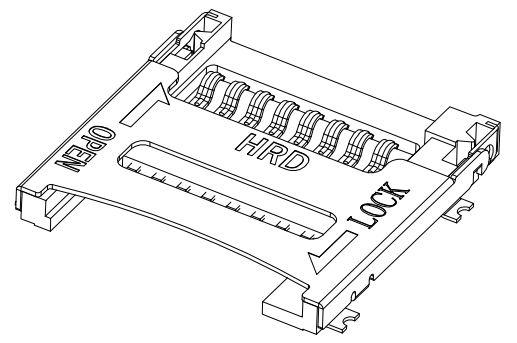
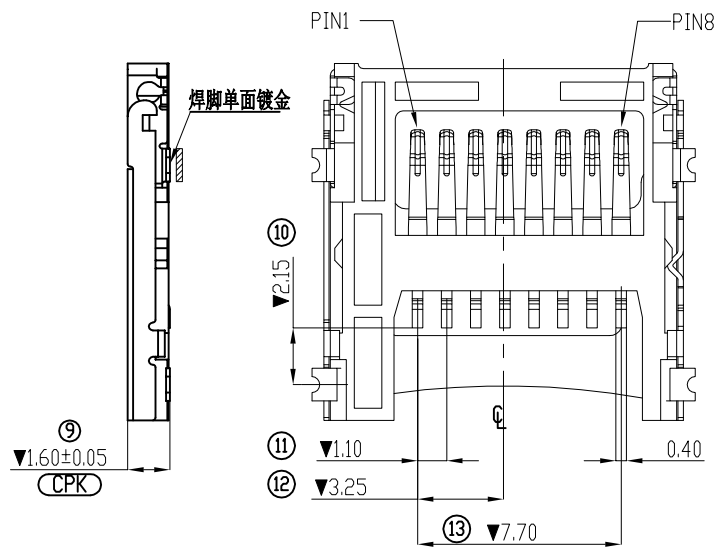
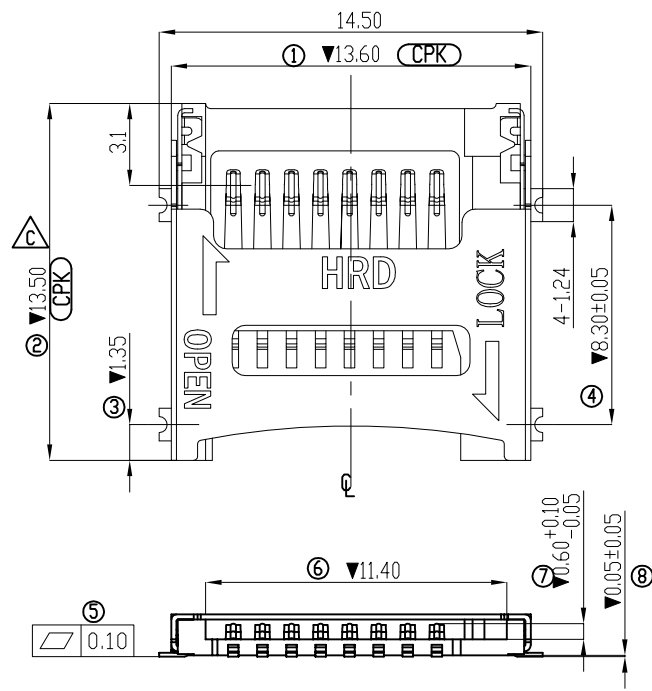
B

C

D

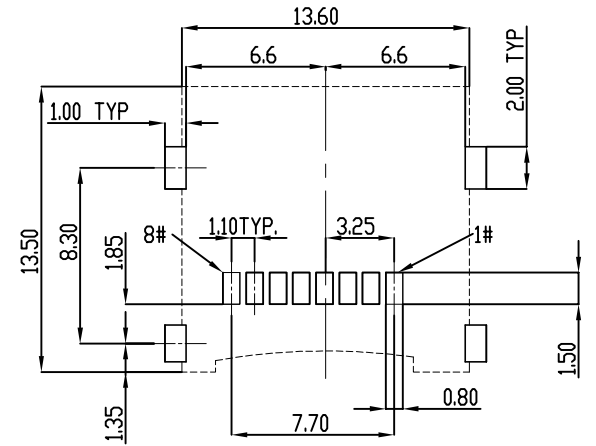
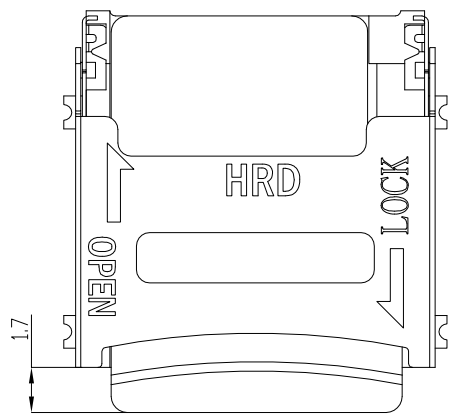
E

F



| T-CARD PIN NO. | PIN NO. |
|----------------|---------|
| T1 | DAT2 |
| T2 | CD/DAT3 |
| T3 | CMD |
| T4 | VDD |
| T5 | CLK |
| T6 | VSS |
| T7 | DAT0 |
| T8 | DAT1 |

NOTE:
 1.MATERIAL:
 HOUSING:HI-TEMP PLASTIC,BLACK,UL94V-0
 CONTACT: COPPER ALLOY,T=0.15±0.01mm
 SHELL:STAINLESS STEEL,T=0.20±0.01mm
 PEG: COPPER ALLOY,T=0.15±0.01mm
 2.FINISH:
 CONTACT:
 50u" NI MIN UNDERPLATED OVERALL
 60~200U" Tin PLATING ON SOLDER AREA
 GOLD FLASH 1~3U" DN CONTACT AREA
 PEG:
 50u" NI MIN UNDERPLATED OVERALL
 GOLD FLASH 1~3U" DN SOLDER AREA
 3.SPECIFICATIONS:
 3-1.Rated Current: 2A
 3-2.Rated Voltage: 12V AC
 3-3.Operating temperature: -30℃ to 85℃
 3-4.Storage temperature: -30℃ to 85℃
 4.Durability:3000 cycles
 5.GP PASSED ACCORD WITH RoHS STANDARD.
 6.ALL DIMENSIONS MARKED▼MUST BE CONTROLLED BY QC.



RECOMMENDED PCB PATTERN LAYOUT
 TOLERANCE: ± 0.05

| | | | | | | | |
|------|-----------|-------------------|------------|----------------|-----------------------|--|--|
| H | E2010012R | 增加焊板面铁壳避让, 缩减焊板尺寸 | 10/16/2020 | UNITS: mm | GENERAL TOLERANCE | DRAW: | PART NO: T02-BB80F160 |
| G | E2008001R | 升级版本 | 08/10/2020 | DATE: 04/14/15 | X. ±0.25 X.* ±2.00 | CHECKED: | NAME: TRANS FLASH CARD CONN. HINGE TYPE 1.6H |
| F | E1705013A | 调整端子结构, 增加端子正向力 | 05/28/2017 | SCALE: 4:1 | .X ±0.20 X.* ±1.00 | APPROVE: | DRAWING NO: C-T02-0000 |
| E | E1603066A | 优化自动机制程 | 03/08/2016 | SHEET: 1/1 | .XX ±0.15 .XX.* ±0.50 | 鸿日达科技股份有限公司 HONGRIDA ELECTRONIC TECHNOLOGY CO.,LTD. | |
| REV. | ECN NO. | DESCRIPTION | DATE | REV. A | FINISH: SEE NOTE | | |